IPC ASSOCIATION CO	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribu				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					ion			
Supplier In	nformation														
Company name* Company unique ID					Unique ID Authority				Respo	Response Date*					
nsemi											2024-0	2024-05-03			
				Title - Contact			Phone - Contact*				Email	Email - Contact*			
Product-Env	y-Stewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title				Representative]	Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards			Product Env	roduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
R	equester Item Number	Mfr Iten	em Number Mfr Item Name				Effective Date	Version	n]	Manufacturing Site		Weight*	UOM	Unit Type	
		QT6231	2	BBIC6.A0 Tri-Bar Baseband IC 4x4 (2024-05-03		,	ΓWU		723.876	mg	Each	
	uring Process Informa						D 1 D				1.00		AD 0 0		
	8 - m m		,		-STD-020 MSI	L Rating		Peak Process Body Temperature Max Time at Pe		T .			eles		
Sn	AgCu		CU Alloy	3	3		260		C	30	seco	onds 3			
omments															
	N: MSL 3 Rated item requir		` `												
or more info	ormation regarding materia	l composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybrominated Biphenyls (Pl	aterial for Cadmium and quantity limit of 0.1% by BB), Polybrominated Diphenyl Ethers (PBDE), an								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per	the definition above except for defined Ro	oHS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recruired by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	138.921	mg	Supplier	Silicon (Si)	7440-21-3		138.921	mg
Insulating Layer	26.01	mg		Epoxy resin	proprietary data		0.8323	mg
			Supplier	Miscellaneous	Trade Secret		10.8462	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		2.2629	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		9.8058	mg
			Supplier	Formaldehyde Polymer	9003-36-5		2.2629	mg
Insulating Mold	11.0	mg		Hardeness	proprietary data		0.891	mg
			Supplier	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6		0.2959	mg
			Supplier	Misc.	Proprietary Data		0.2959	mg
			Supplier	Carbon Black (C)	1333-86-4		0.055	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		7.6879	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.7743	mg
Solder Ball	135.578	mg	Supplier	Silver (Ag)	7440-22-4		4.0673	mg
			Supplier	Tin (Sn)	7440-31-5		130.8328	mg
			Supplier	Copper (Cu)	7440-50-8		0.6779	mg
Solder Mask	20.086	mg		Epoxy resin	proprietary data		7.6327	mg
			Supplier	3-methoxy-3-methylbutylacetate	103429-90-9		2.6112	mg
			Supplier	Miscellaneous	Trade Secret		0.8034	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		2.6112	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.0086	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5		1.6069	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.812	mg
Substrate - Bump	5.483	mg	Supplier	Silver (Ag)	7440-22-4		0.1645	mg
			Supplier	Tin (Sn)	7440-31-5		5.2911	mg
			Supplier	Copper (Cu)	7440-50-8		0.0274	mg
Substrate - Core Material	237.037	mg		Other Epoxy resins	proprietary data		71.1111	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		71.1111	mg
			Supplier	Copper (Cu)	7440-50-8		94.8148	mg
Substrate Plating-Cu	141.406	mg	Supplier	Copper (Cu)	7440-50-8		141.406	mg
Substrate - Plugging	8.355	mg	Supplier	2-Oxiranemethanamine,N-[2-methyl-4-(2-oxiranylmethoxy)phenyl]-N-(2-oxiranylmethyl)	110656-67-2		1.2533	mg

	Supplier	Miscellaneous	Trade Secret	3.7597	mg
	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6	2.5065	mg
	Supplier	Formaldehyde Polymer	9003-36-5	0.8355	mg